MOSFETs Silicon N-channel MOS (U-MOSX-H)

# TK5R3E08QM

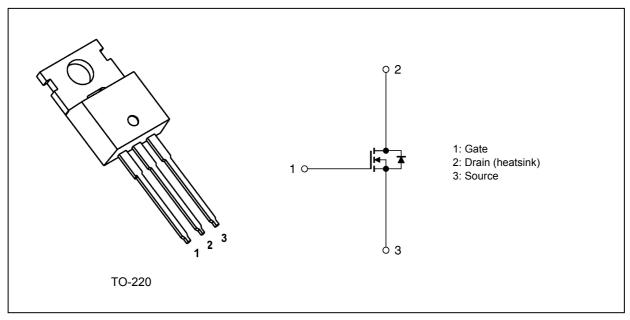
#### 1. Applications

- High-Efficiency DC-DC Converters
- Switching Voltage Regulators
- Motor Drivers

### 2. Features

- (1) High-speed switching
- (2) Small gate charge:  $Q_{SW} = 17 \text{ nC}$  (typ.)
- (3) Small output charge:  $Q_{oss} = 66 \text{ nC}$  (typ.)
- (4) Low drain-source on-resistance:  $R_{DS(ON)} = 4.2 \text{ m}\Omega$  (typ.) ( $V_{GS} = 10 \text{ V}$ )
- (5) Low leakage current:  $I_{DSS} = 10 \ \mu A (max) (V_{DS} = 80 \ V)$
- (6) Enhancement mode:  $V_{th}$  = 2.5 to 3.5 V ( $V_{DS}$  = 10 V,  $I_D$  = 0.7 mA)

### 3. Packaging and Internal Circuit



#### 4. Absolute Maximum Ratings (Note) ( $T_a = 25 \ ^{\circ}C$ unless otherwise specified)

| Characteristi                  | Symbol                   | Rating             | Unit             |            |       |
|--------------------------------|--------------------------|--------------------|------------------|------------|-------|
| Drain-source voltage           |                          |                    | V <sub>DSS</sub> | 80         | V     |
| Gate-source voltage            |                          |                    | V <sub>GSS</sub> | ±20        |       |
| Drain current (DC)             | (T <sub>c</sub> = 25 °C) | (Note 1)           | Ι <sub>D</sub>   | 120        | Α     |
| Drain current (DC)             | (Silicon limit)          | (Note 1), (Note 2) | ID               | 126        |       |
| Drain current (pulsed)         | (t = 100 μs)             | (Note 1)           | I <sub>DP</sub>  | 320        |       |
| Power dissipation              | (T <sub>c</sub> = 25 °C) |                    | PD               | 150        | W     |
| Single-pulse avalanche energy  | ·                        | (Note 3)           | E <sub>AS</sub>  | 49         | mJ    |
| Single-pulse avalanche current |                          | (Note 3)           | I <sub>AS</sub>  | 85         | Α     |
| Channel temperature            |                          |                    | T <sub>ch</sub>  | 175        | °C    |
| Storage temperature            |                          |                    | T <sub>stg</sub> | -55 to 175 |       |
| Mounting torque                |                          |                    | TOR              | 0.6        | N · m |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

| Characteristics                       | Symbol                   | Max                   | Unit |      |
|---------------------------------------|--------------------------|-----------------------|------|------|
| Channel-to-case thermal resistance    | (T <sub>c</sub> = 25 °C) | R <sub>th(ch-c)</sub> | 0.99 | °C/W |
| Channel-to-ambient thermal resistance | (T <sub>a</sub> = 25 °C) | R <sub>th(ch-a)</sub> | 83.3 |      |

Note 1: Ensure that the channel temperature does not exceed 175 °C.

Note 2: Limited 120 A by package capability.

Note 3: V\_DD = 64 V, L = 5.3  $\mu H, \, I_{AS}$  = 85 A

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

### 6. Electrical Characteristics

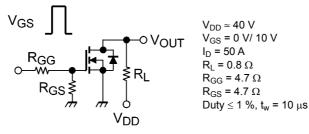
### 6.1. Static Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

| Characteristics                         | Symbol               | Test Condition                                  | Min | Тур. | Max  | Unit |
|---|----------------------|---|-----|------|------|------|
| Gate leakage current                    | I <sub>GSS</sub>     | $V_{GS}$ = ±20 V, $V_{DS}$ = 0 V                | _   | _    | ±0.1 | μA   |
| Drain cut-off current                   | I <sub>DSS</sub>     | $V_{DS}$ = 80 V, $V_{GS}$ = 0 V                 | _   | —    | 10   |      |
| Drain-source breakdown voltage          | V <sub>(BR)DSS</sub> | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V   | 80  | —    | _    | V    |
| Drain-source breakdown voltage (Note 4) | V <sub>(BR)DSX</sub> | $I_{D}$ = 10 mA, $V_{GS}$ = -20 V               | 60  | —    | _    |      |
| Gate threshold voltage                  | V <sub>th</sub>      | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.7 mA | 2.5 | —    | 3.5  |      |
| Drain-source on-resistance              | R <sub>DS(ON)</sub>  | V <sub>GS</sub> = 6 V, I <sub>D</sub> = 32 A    | _   | 5.3  | 7.3  | mΩ   |
|   |                      | $V_{GS}$ = 10 V, I <sub>D</sub> = 50 A          | _   | 4.2  | 5.3  |      |

Note 4: If a reverse bias is applied between gate and source, this device enters V<sub>(BR)DSX</sub> mode. Note that the drainsource breakdown voltage is lowered in this mode.

### 6.2. Dynamic Characteristics ( $T_a = 25$ °C unless otherwise specified)

| Characteristics                | Symbol           | Test Condition   | Min | Тур. | Max | Unit |
|--------------------------------|------------------|--|-----|------|-----|------|
| Input capacitance              | C <sub>iss</sub> | V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V, f = 1 MHz | _   | 3980 | _   | pF   |
| Reverse transfer capacitance   | C <sub>rss</sub> |  | _   | 55   | —   |      |
| Output capacitance             | C <sub>oss</sub> |  | _   | 1000 | _   |      |
| Gate resistance                | r <sub>g</sub>   | —  | _   | 1.7  | 2.6 | Ω    |
| Switching time (rise time)     | t <sub>r</sub>   | See Fig. 6.2.1   | _   | 81   | —   | ns   |
| Switching time (turn-on time)  | t <sub>on</sub>  |  | _   | 99   | _   |      |
| Switching time (fall time)     | t <sub>f</sub>   |  | _   | 81   | _   |      |
| Switching time (turn-off time) | t <sub>off</sub> |  | _   | 130  | _   |      |



#### Fig. 6.2.1 Switching Time Test Circuit

### 6.3. Gate Charge Characteristics ( $T_a = 25$ °C unless otherwise specified)

| Characteristics                     | Symbol           | Test Condition   | Min | Тур. | Max | Unit |
|-------------------------------------|------------------|--|-----|------|-----|------|
| Total gate charge (gate-source plus | Qg               | $V_{DD}\approx 40$ V, $V_{GS}$ = 10 V, $I_{D}$ = 50 A    | _   | 55   | _   | nC   |
| gate-drain)                         |                  | $V_{DD} \approx 40$ V, $V_{GS}$ = 6 V, $I_D$ = 32 A      | _   | 33   | _   |      |
| Gate-source charge 1                | Q <sub>gs1</sub> | $V_{DD} \approx 40$ V, $V_{GS}$ = 10 V, $I_D$ = 50 A     | _   | 17   | _   |      |
| Gate-drain charge                   | Q <sub>gd</sub>  |  | _   | 12   | _   |      |
| Gate switch charge                  | Q <sub>SW</sub>  |  | _   | 17   | _   |      |
| Output charge                       | Q <sub>oss</sub> | V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V, f = 1 MHz | _   | 66   | _   |      |

### 6.4. Source-Drain Characteristics ( $T_a = 25$ °C unless otherwise specified)

| Characteristics                        | Symbol           | Test Condition                                 | Min | Тур. | Max  | Unit |
|--|------------------|--|-----|------|------|------|
| Reverse drain current (pulsed) (Note 5 | )                | —  | —   | —    | 320  | A    |
| Diode forward voltage                  | V <sub>DSF</sub> | I <sub>DR</sub> = 50 A, V <sub>GS</sub> = 0 V  | _   | _    | -1.2 | V    |
| Reverse recovery time                  | t <sub>rr</sub>  | I <sub>DR</sub> = 30 A, V <sub>GS</sub> = 0 V, | _   | 48   | _    | ns   |
| Reverse recovery charge                | Q <sub>rr</sub>  | -dI <sub>DR</sub> /dt = 100 A/μs               |     | 53   | _    | nC   |

Note 5: Ensure that the channel temperature does not exceed 175 °C.

### 7. Marking

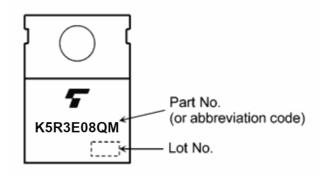
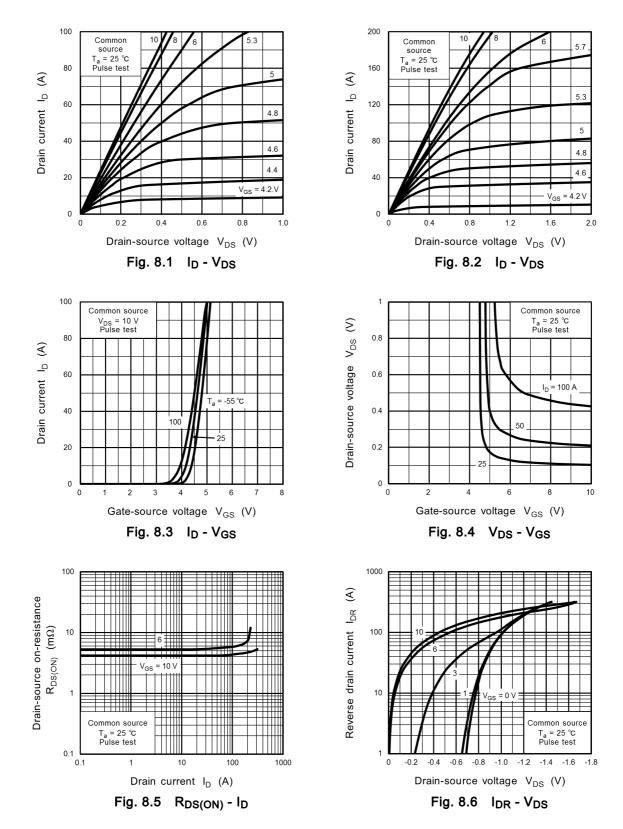


Fig. 7.1 Marking

### 8. Characteristics Curves (Note)



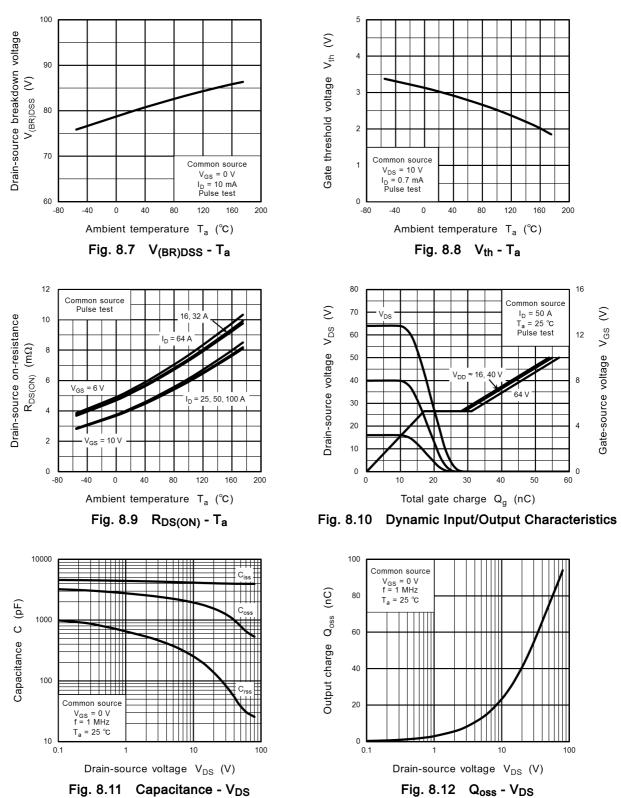
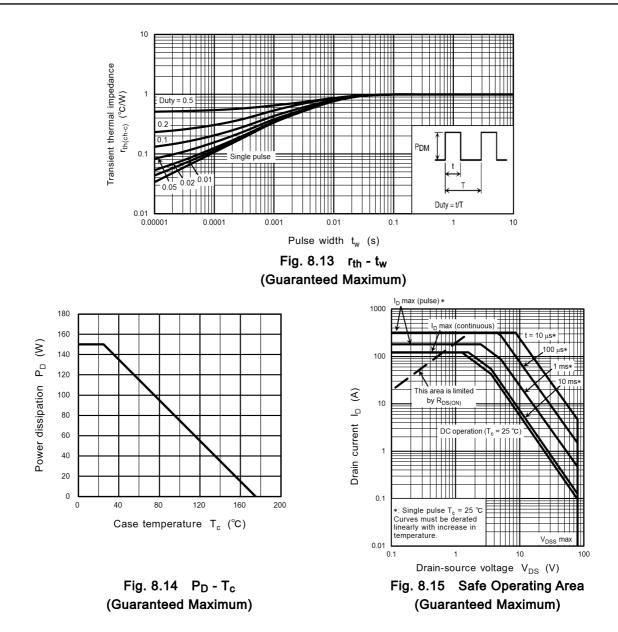


Fig. 8.11 Capacitance - V<sub>DS</sub>

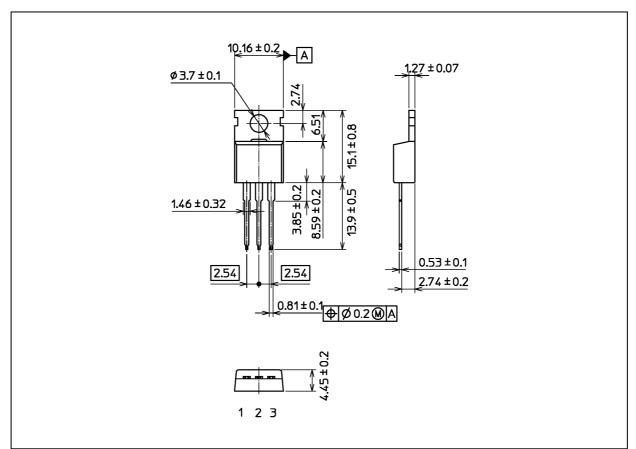


Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

## TK5R3E08QM

### **Package Dimensions**

Unit: mm



#### Weight: 1.96 g (typ.)

| Pack             | age Name(s) |
|------------------|-------------|
| TOSHIBA: 2-10X1A |             |
| Nickname: TO-220 |             |

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